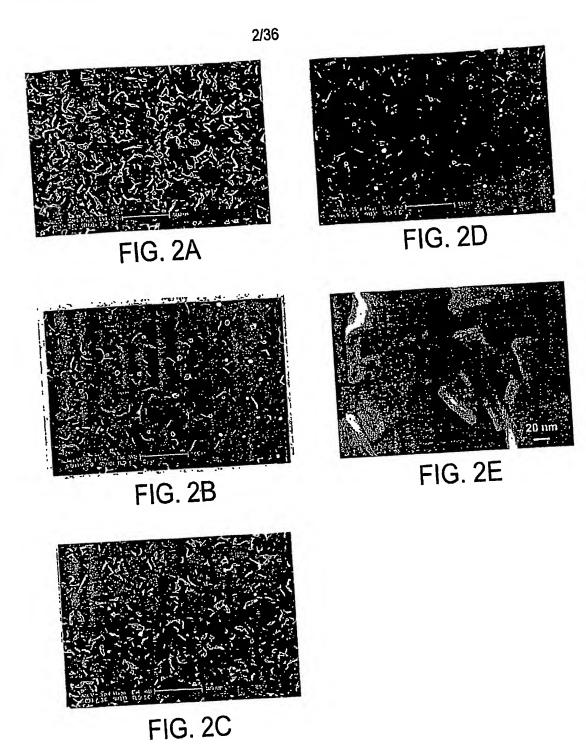


FIG. 1

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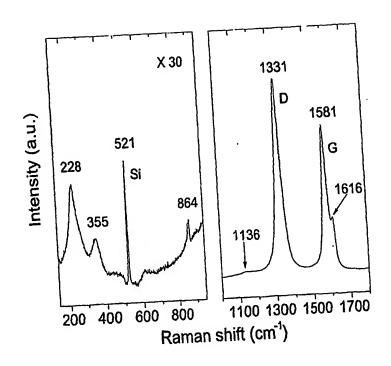


FIG. 3

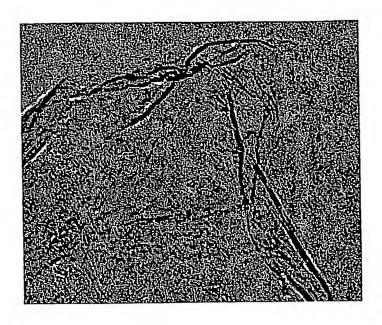


FIG. 4

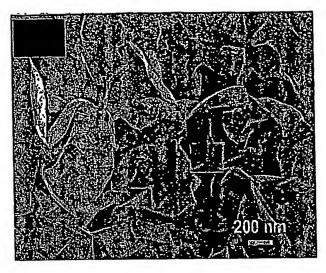


FIG. 5A

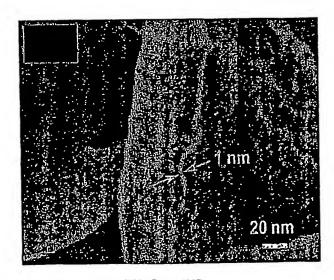


FIG. 5B

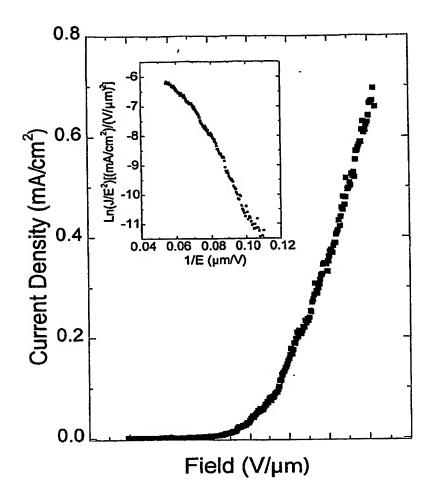


FIG. 6

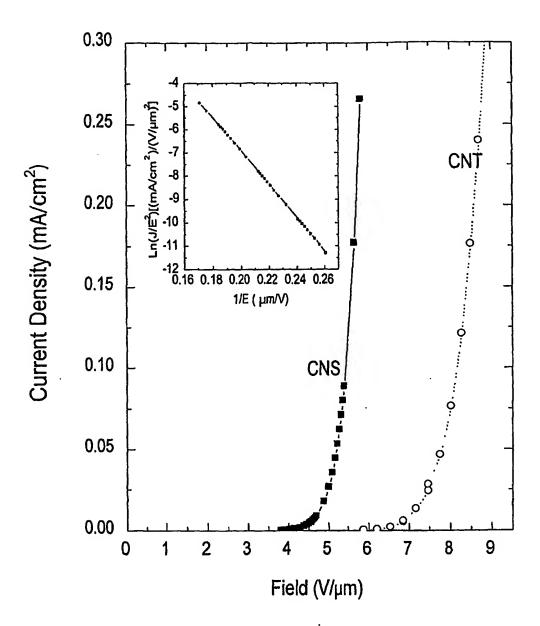


FIG. 7

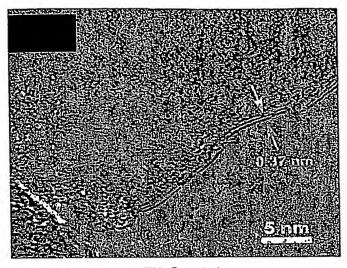


FIG. 8A

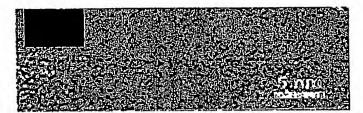


FIG. 8B

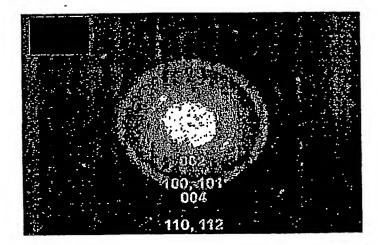


FIG. 8C

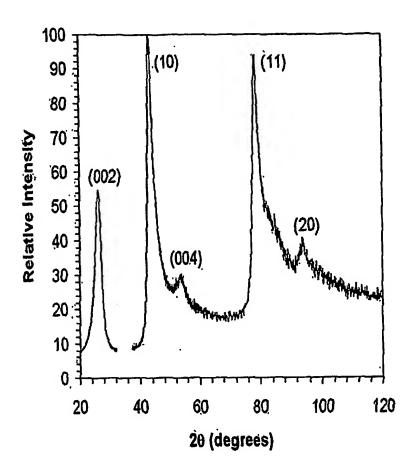


FIG. 9

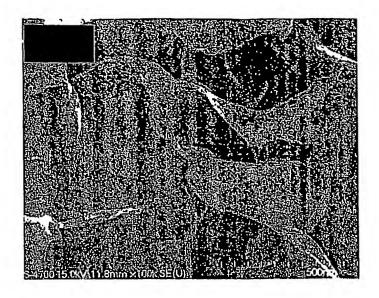


FIG. 10A

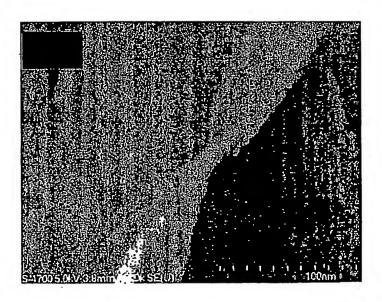


FIG. 10B

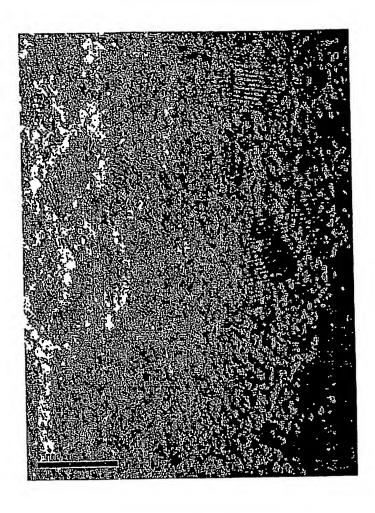


FIG. 11

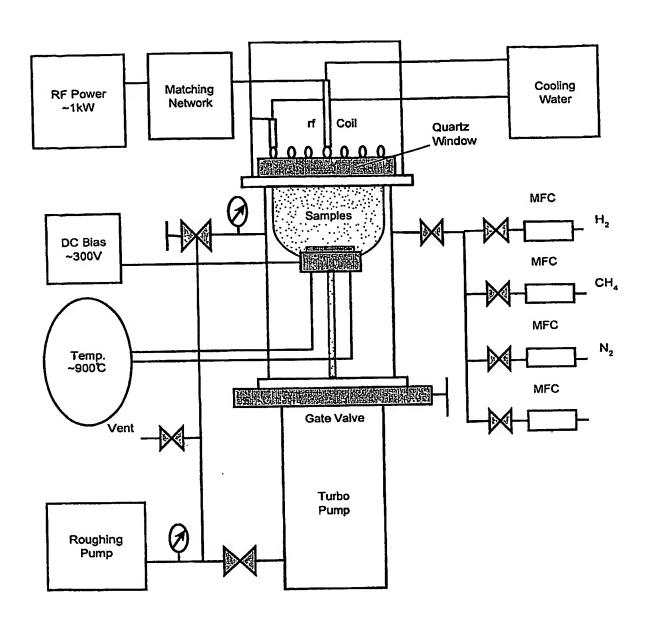


FIG. 12

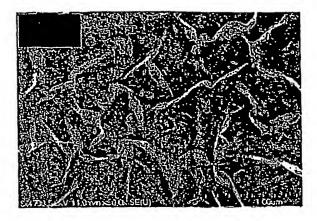


FIG. 13A

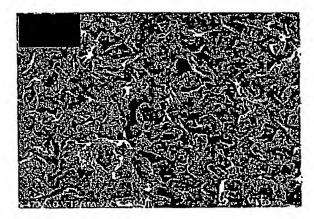


FIG. 13B

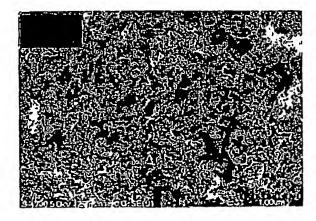


FIG. 13C

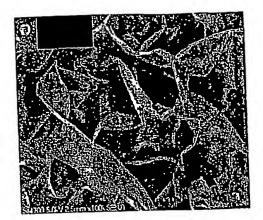


FIG. 14A

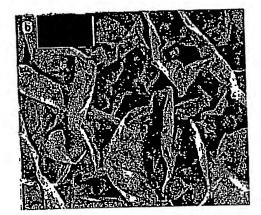


FIG. 14B



FIG. 14C

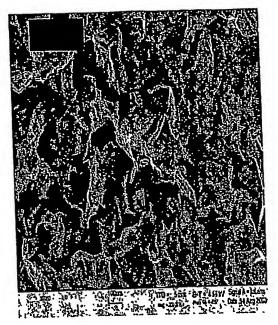


FIG. 14D

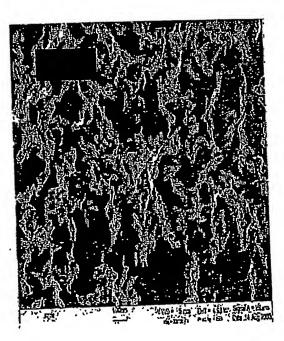


FIG. 14E

# Nanosphere Lithography Approach to Carbon Nanotube

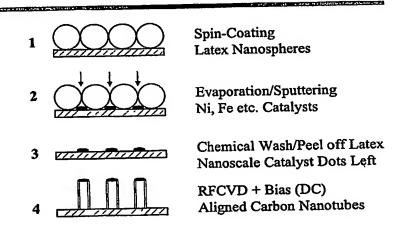
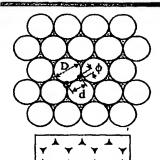


FIG. 15

## Latex Nanosphere Lithography Pattern (Single-Layer)



Intersphere hole spacing:

$$d_{SL} = \frac{D}{\sqrt{3}} = 0.577D$$

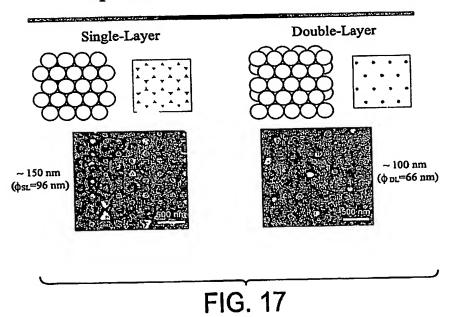
Intersphere hole equivalent diameter:

$$\phi_{SL} = \left[ \frac{4}{\pi} \cdot \left( \frac{1}{2} \cdot \frac{\sqrt{3}}{2} \cdot \frac{1}{4} \cdot \frac{1}{6} \cdot 3 \cdot \pi \right) \right]^{\frac{1}{2}} D \approx 0.23D$$

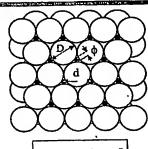
D, nm	419	269	171	100 .
d <sub>SL</sub> , nm	241	155	99	58
ф <sub>SL</sub> , nm	96	62	39	23

FIG. 16

### Comparison of SL and DL Patterns



### Latex Nanosphere Double-Layer Pattern



Intersphere hole spacing:

$$d_{DL} = D$$

Intersphere hole equivalent diameter:

$$\phi_{DL} \approx \left[\frac{4}{\pi} \cdot 6 \cdot \frac{1}{2} \cdot \frac{0.155}{2} \cdot 2 \cdot tg30 \cdot \frac{0.155}{2}\right]^{\frac{1}{2}} D \approx 0.16D$$

•		•		•		•	
	•		•		•		
•		•		•		•	l
	_				_		l

D, nm	419	269	171	100
d <sub>SL</sub> , nm	241	155	99	58
?SL nm	66	43	27	16

FIG. 18

Annealing of Ni Nanoscale Patterns - I Single-layer latex mask

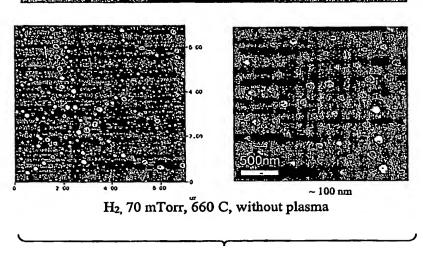


FIG. 19

Annealing of Ni Nanoscale Patterns - II

Double-layer latex mask

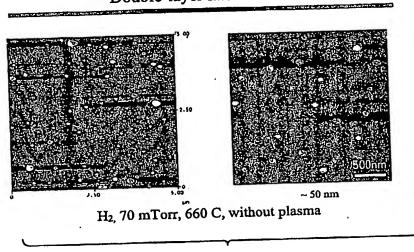


FIG. 20

## Latex Nanosphere Masks (AFM Images)

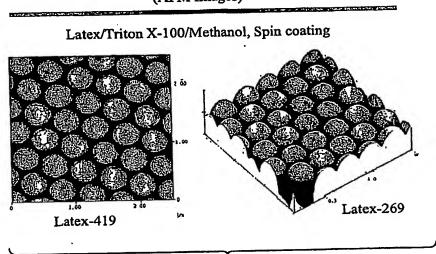


FIG. 21

## Defects of Latex Nanosphere Mask

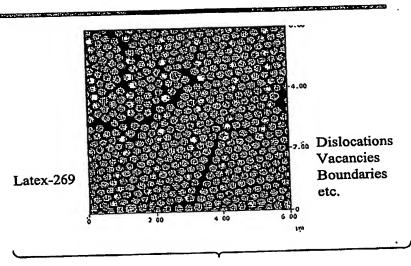


FIG. 22

# Ni Pattern via E-Beam Evaporation (20 nm, latex-419 mask)

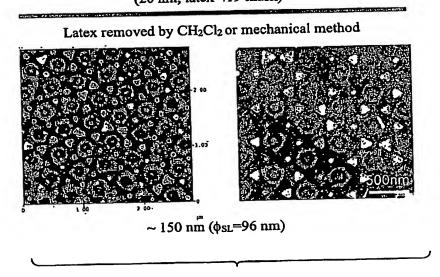


FIG. 23

### Schematic of RF-CVD System

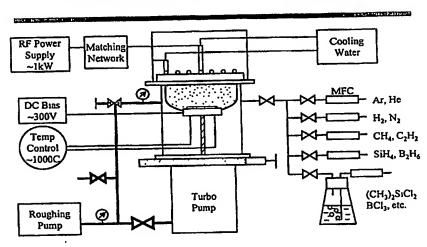


FIG. 24

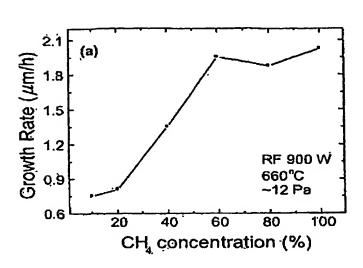


FIG. 25A

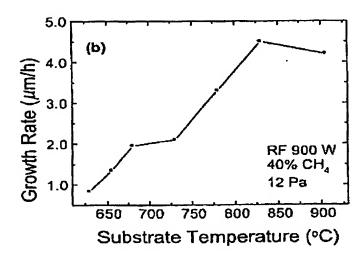


FIG. 25B

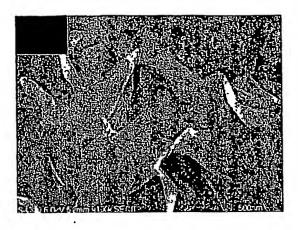


FIG. 26A

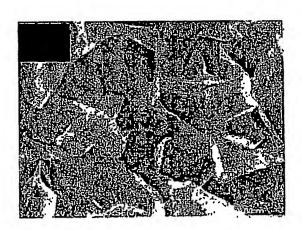


FIG. 26B

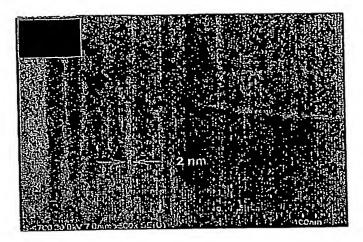


FIG. 27A

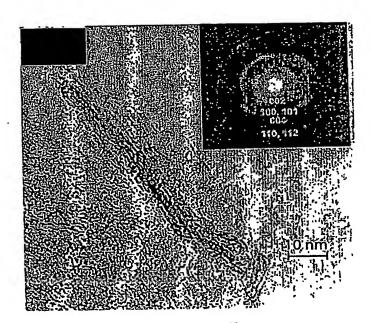


FIG. 27B

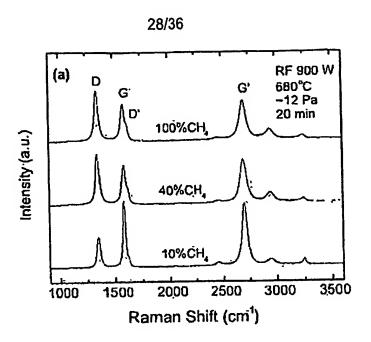


FIG. 28A

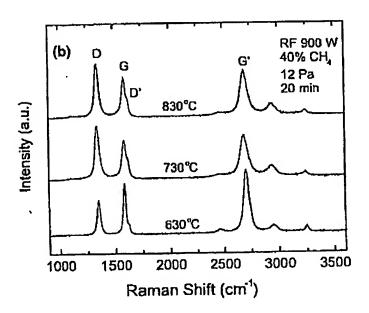


FIG. 28B

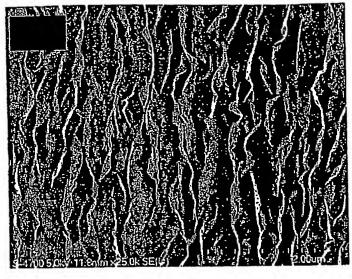


FIG. 29A

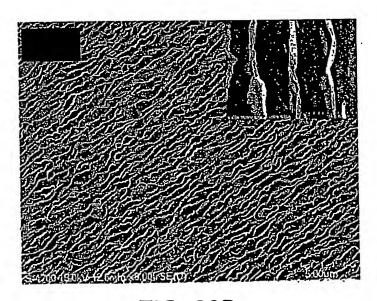


FIG. 29B

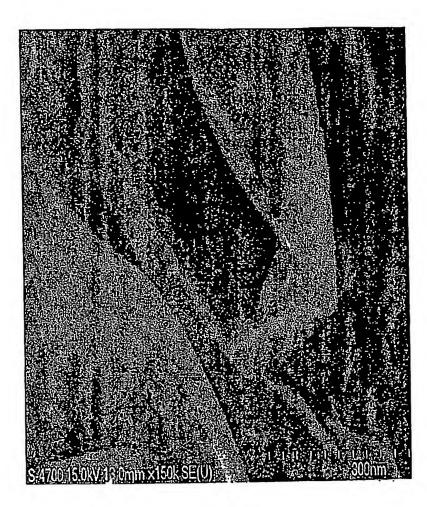


FIG. 30

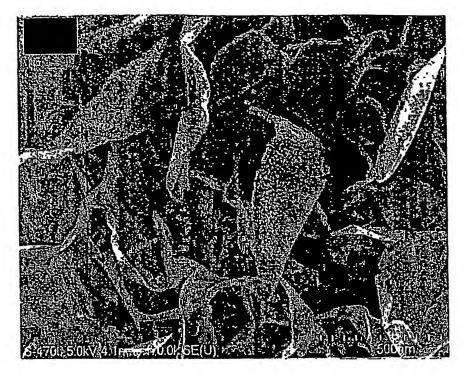


FIG. 31A



FIG. 31B

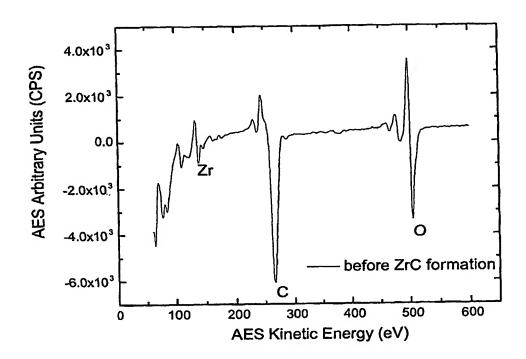


FIG. 32

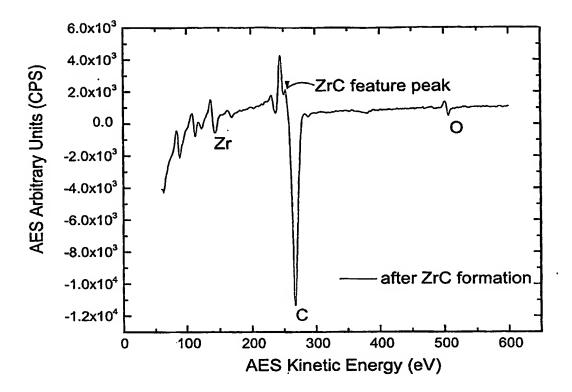


FIG. 33

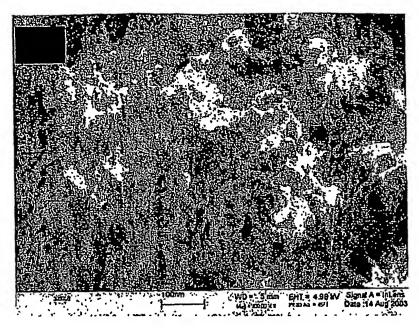


FIG. 34A



FIG. 34B

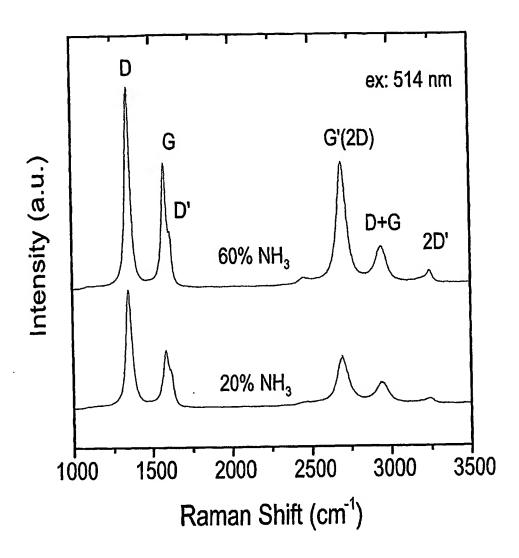


FIG. 35

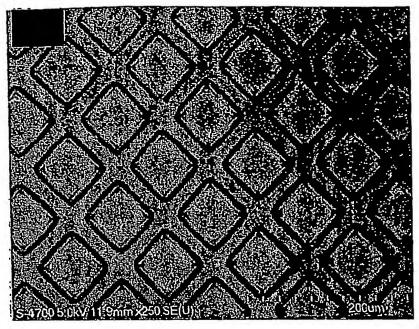


FIG. 36A



FIG. 36B

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